

## SECTION 1 - SERVICING

### 1. Preventive Maintenance Procedures

Contains routine maintenance instructions for cleaning and inspecting the Test Set.

**CAUTION:** DISCONNECT POWER FROM TEST SET TO AVOID POSSIBLE DAMAGE TO ELECTRONIC CIRCUITS.

#### A. External Cleaning

STEP	PROCEDURE
1.	Clean front panel and display face with soft lint-free cloth. If dirt is difficult to remove, dampen cloth with water and mild liquid detergent.
2.	Remove grease, fungus and ground-in dirt from surfaces with soft lint-free cloth dampened (not soaked) with isopropyl alcohol.
3.	Remove dust and dirt from connectors with soft-bristled brush.
4.	Cover connectors, not in use, with suitable dust cover to prevent tarnishing of connector contacts.
5.	Clean cables with soft lint-free cloth.
6.	Paint exposed metal surface to avoid corrosion.

#### B. Internal Cleaning



**CAUTION:** DO NOT MOVE COMPONENTS ON CIRCUIT BOARDS OR DISASSEMBLE CONNECTORS NEEDLESSLY TO AVOID POSSIBLE DAMAGE.

**CAUTION:** DO NOT OPEN COMPLEX INTERNAL MODULES FOR SOLE PURPOSE OF CLEANING AND INSPECTION.

Remove dust with hand-controlled dry air jet of 15 psi (1.054 kg/cm<sup>2</sup>) and wipe internal chassis parts and frame with soft lint-free cloth moistened with isopropyl alcohol.

C. Visual Inspection

STEP	PROCEDURE
1.	Inspect Chassis for: <ul style="list-style-type: none"> <li>● Tightness of sub-assemblies and chassis mounted connectors.</li> <li>● Corrosion or damage to metal surfaces.</li> </ul>
2.	Inspect Capacitors for: <ul style="list-style-type: none"> <li>● Loose mounting, deformities or obvious physical damage.</li> <li>● Leakage or corrosion around leads.</li> </ul>
3.	Inspect Connectors for: <ul style="list-style-type: none"> <li>● Loose or broken parts, cracked insulation and bad contacts.</li> </ul>
4.	Inspect Circuit Boards for: <ul style="list-style-type: none"> <li>● Corrosion or damage to connectors.</li> <li>● Damage to mounted components including crystals and ICs.</li> <li>● Freedom from foreign material.</li> </ul>
5.	Inspect Resistors for: <ul style="list-style-type: none"> <li>● Cracked, broken, charred or blistered bodies.</li> <li>● Loose or corroded soldering connections.</li> </ul>
6.	Inspect Semiconductors for: <ul style="list-style-type: none"> <li>● Cracked, broken, charred or discolored bodies.</li> <li>● Correct placement and condition of seals around leads.</li> </ul>
7.	Inspect Wiring for: <ul style="list-style-type: none"> <li>● Broken or loose ends and connections.</li> <li>● Proper dress relative to other chassis parts.</li> </ul> <p><b>NOTE:</b> Verify wrapped wiring is tight.</p>